

Agenda

March 12, 2018

iNEMI Presentations

9:00 a.m. PDT	Introductions and iNEMI Overview: David Godlewski, iNEMI
9:15 a.m.	Project Updates: Development of Cleanliness Specification for Expanded Beam Connectors Project, Phase 2: Tatiana Berdinskikh, Celestica
9:30 a.m.	Sample Preparation & Evaluation: Tom Mitcheltree, USConec
10:00 a.m.	Contamination Technique for Prism MT Ferrules in MXC Connectors for Optical Performance Studies: Doug Wilson, FiberQA
10:30 a.m.	Data Analysis and Preliminary Results: Michael Kadar-Kallen, CommScope
11:00 a.m.	MM Fiber Connection Loss under EF Launched Condition — Ray Tracing Simulation and Experimental Results: Toshiaki Satake, USCONEC
11:30 a.m.	Expanded Beam Connectors under Dust: Modeling and Measurement: Ke Wang, US Conec
12:00 – 1: 00 pm	BREAK FOR LUNCH
1.00 p.m.	Cleaning Solutions for Expanded Beam Connector: Tiger Ninomiya, Senko; Bernard Lee, Senko
1:20 p.m.	Scratch Analysis for IEC SC86B WG4 Round Robin: Doug Wilson, FiberQA; Vitalina Rudyk, Sumix; Gang He, EXFO

For additional information about iNEMI projects, please contact David Godlewski, iNEMI, at dgodlewski@inemi.org

AIM Photonics Academy Presentations

2:00 – 5:00 pm

- Grand Challenges and Key Needs: Professor Lionel Kimerling, AIM Academy Executive, MIT
- 2018 Project Focus of IPSR: Robert Pfahl, Director of Roadmapping, IPSR
- Board Level Optical Interconnect Program: Terry Smith, Senior Staff Scientist, 3M
 - Phase 1 Single Mode Connector Evaluation: Tom Marrapode, Director of Advanced Technology Development, Molex
 - Phase 2 Chip and Connector Attach & Phase 3 Substrate Evaluation: Terry Smith, 3M
- Application Interest Group (AIG) Process Overview & Potential AIG Areas of Interest: Madelaine Glick, Industrial Liaison Officer, MIT
- Wrap Up: Professor Lionel Kimerling, AIM Academy, MIT

For additional information about IPSR and AIM Photonics, please contact Bob Pfahl, IPSR, bob.pfahl@inemi.org